

Figure 2. bq27x10EVM Topside Assembly

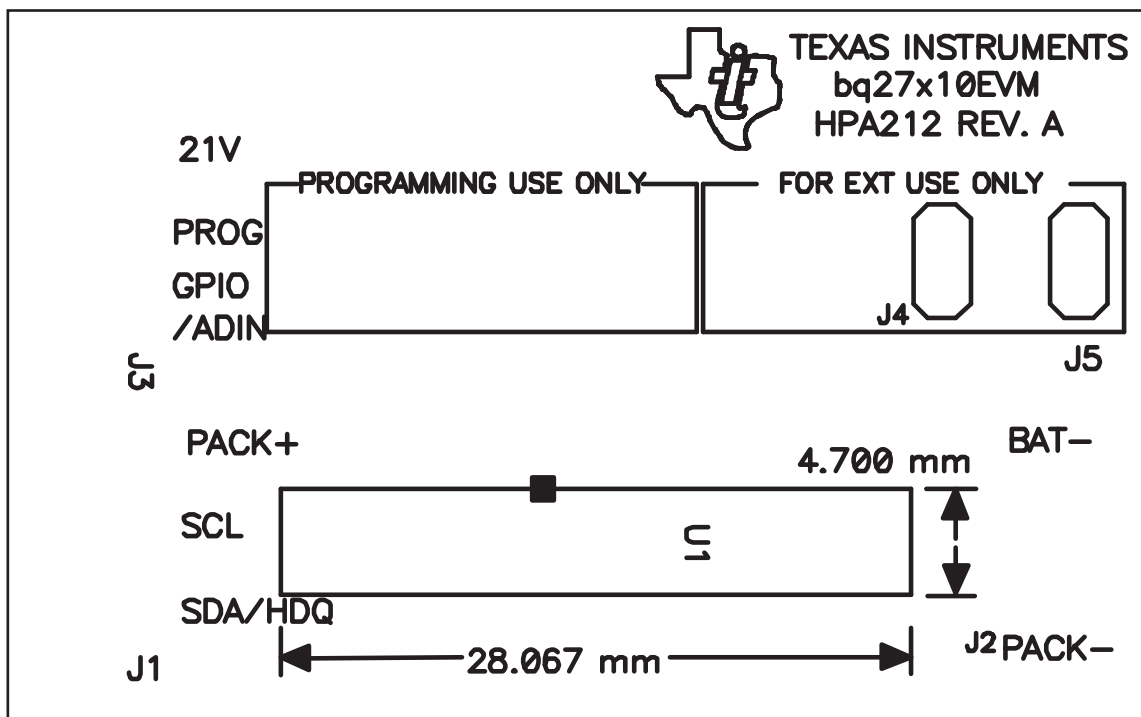


Figure 3. bq27x10EVM Silkscreen

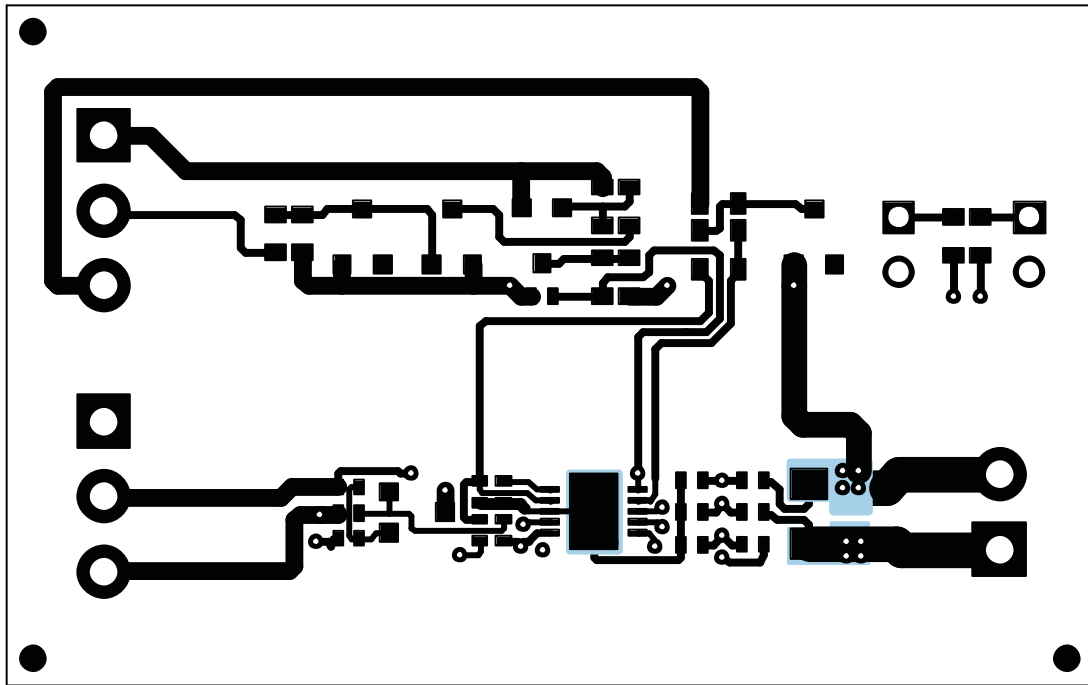


Figure 4. bq27x10EVM Layer 1 Layout

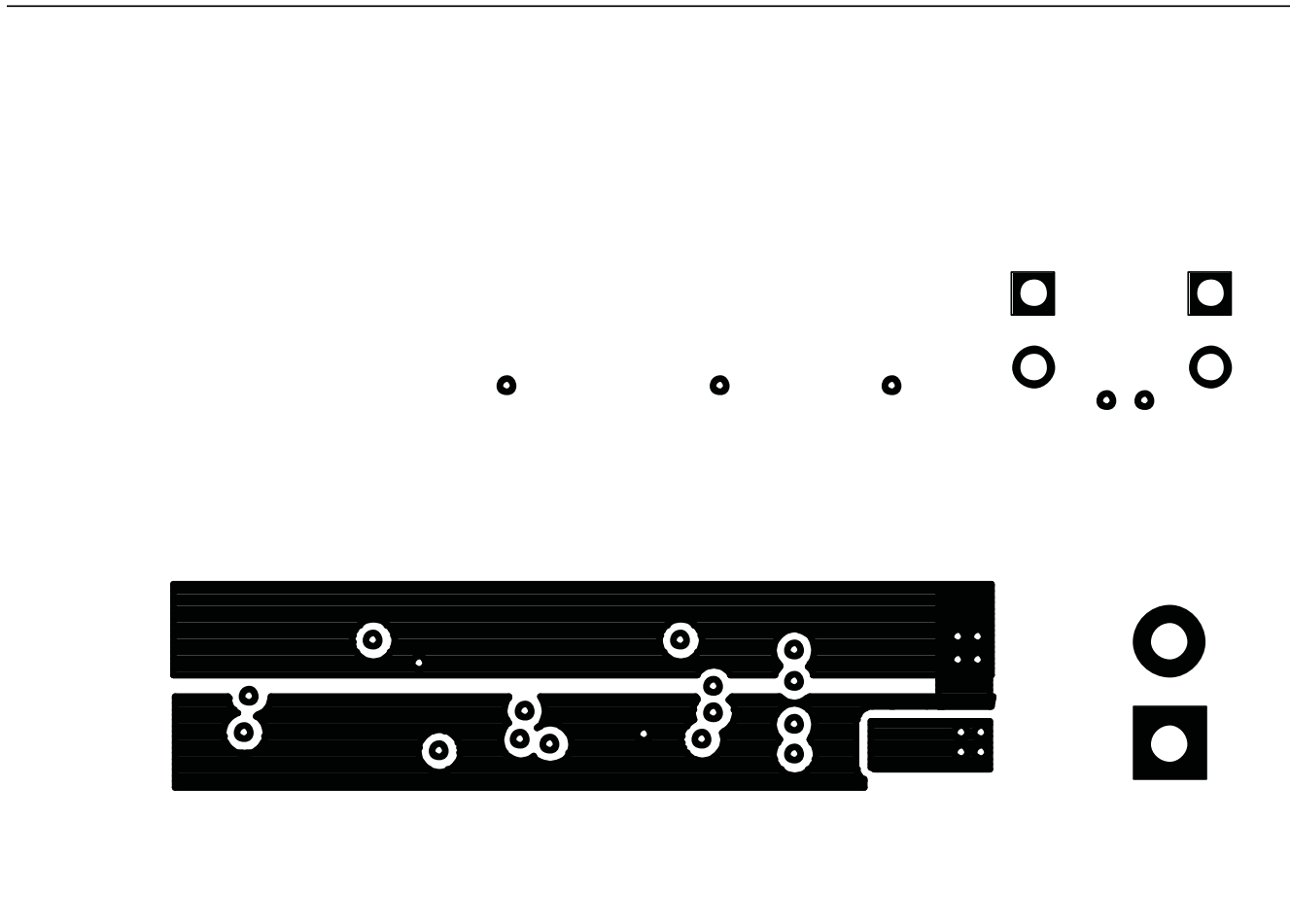


Figure 5. bq27x10EVM Layer 2 Layout

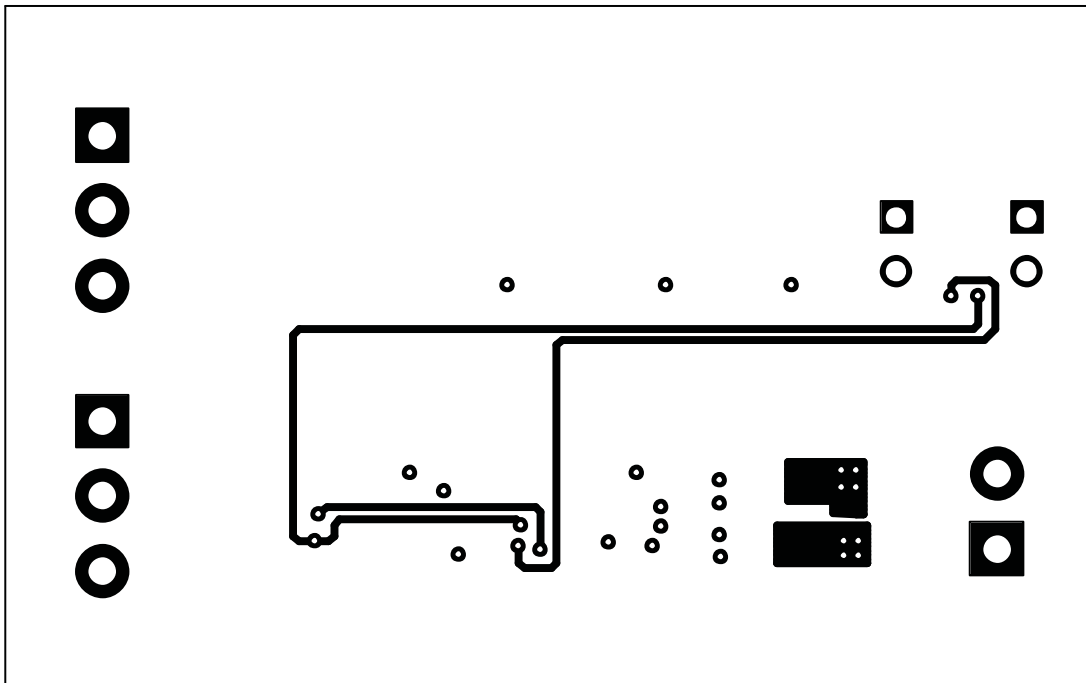


Figure 6. bq27x10EVM Layer 3 Layout

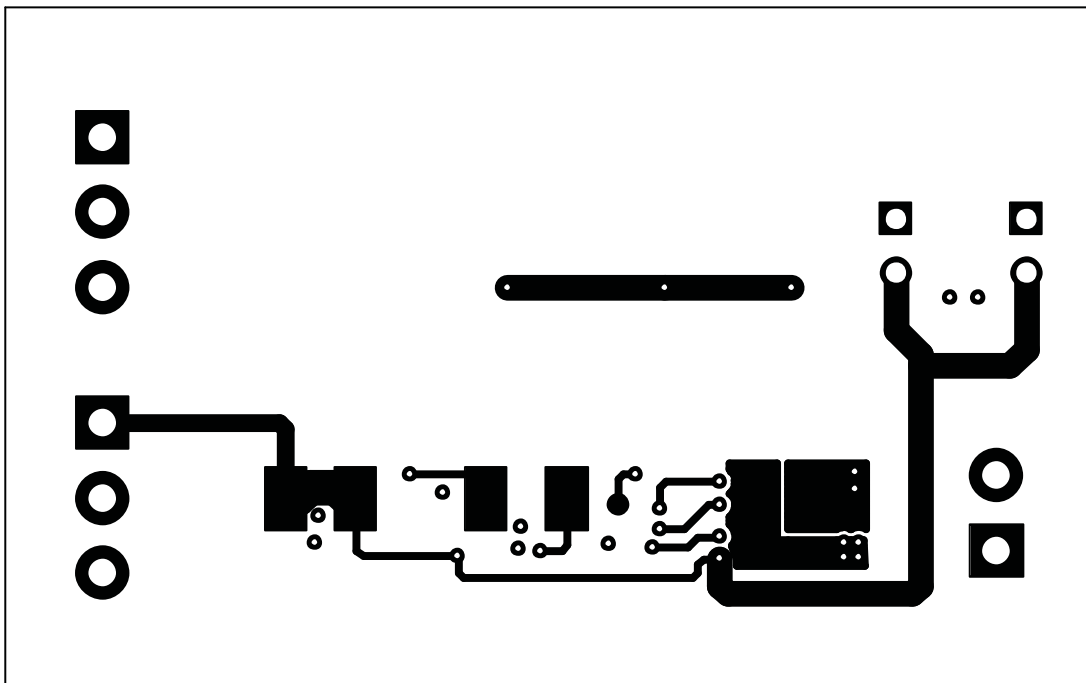


Figure 7. bq27x10EVM Layer 4 Layout

5 bq27x10EVM Circuit Module List of Materials

Table 3 contains the list of materials required for the bq27x10EVM circuit module.

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